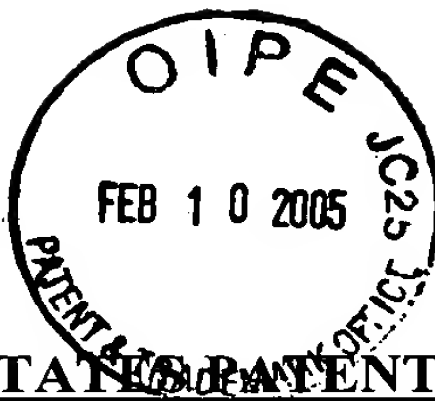


DOCKET NO.: 201225US0/trc



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Minoru TAKAYA, et al.

GROUP: 1714

SERIAL NO: 09/748,261

FILED: December 27, 2000

EXAMINER: CAIN, Edward J.

FOR: COMPOSITE DIELECTRIC MATERIAL, COMPOSITE DIELECTRIC SUBSTRATE, PREPREG, COATED METAL FOIL, MOLDED SHEET, COMPOSITE MAGNETIC SUBSTRATE, SUBSTRATE, DOUBLE SIDE METAL FOIL-CLAD SUBSTRATE, FLAME RETARDANT SUBSTRATE, POLYVINYL BENZYL ETHER RESIN COMPOSITION, THERMOSETTING POLYVINYL BENZYL ETHER RESIN COMPOSITION, AND METHOD FOR PREPARING THERMOSETTING POLYVINYL BENZYL ETHER RESIN COMPOSITION

SUBMISSION OF SUPPLEMENTAL APPLICATION DATA SHEET

Office of Initial Patent Examination
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant(s) submit herewith a Supplemental Application Data Sheet for the above-identified application for the purpose of including priority information for Japan Application 2000-68366.

Respectfully Submitted,

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SUPPLEMENTAL APPLICATION DATA SHEET

APPLICATION INFORMATION

Application Number:: 09/748,261
Application Date:: 12/27/00
Application Type:: REGULAR
Subject Matter:: UTILITY
Suggested Group Art Unit:: 1714
CD-ROM or CD-R?:: NONE
Title:: COMPOSITE DIELECTRIC MATERIAL,
COMPOSITE DIELECTRIC
SUBSTRATE, PREPREG, COATED
METAL FOIL, MOLDED SHEET,
COMPOSITE MAGNETIC SUBSTRATE,
SUBSTRATE, DOUBLE SIDE METAL
FOIL-CLAD SUBSTRATE, FLAME
RETARDANT SUBSTRATE,
POLYVINYLBENZYL ETHER RESIN
COMPOSITION, THERMOSETTING
POLYVINYLBENZYL ETHER RESIN
COMPOSITION, AND METHOD FOR
PREPARING THERMOSETTING
POLYVINYLBENZYL ETHER RESIN
COMPOSITION
Attorney Docket Number:: 201225US0
Total Drawing Sheets:: 64

INVENTOR INFORMATION

Applicant Authority Type:: INVENTOR
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City of Mailing Address::	Tokyo
Country of Mailing Address::	JAPAN
Postal or Zip Code of Mailing Address::	103-8272
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City of Mailing Address::	Tokyo
Country of Mailing Address::	JAPAN
Postal or Zip Code of Mailing Address::	103-8272

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Applicant Authority Type::	INVENTOR
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Applicant Authority Type::	INVENTOR
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Applicant Authority Type:: INVENTOR
 Primary Citizenship Country:: JAPAN
 Status:: FULL CAPACITY
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 Country of Mailing Address:: JAPAN
 Postal or Zip Code of Mailing Address:: 103-8272

CORRESPONDENCE INFORMATION

Correspondence Customer Number:: 22850

REPRESENTATIVE INFORMATION

Representative Customer Number:: 22850

DOMESTIC PRIORITY INFORMATION

FOREIGN PRIORITY INFORMATION

11-373804	Japan	12/28/99	YES
11-373805	Japan	12/28/99	YES
11-373806	Japan	12/28/99	YES
11-373353	Japan	12/28/99	YES
11-375732	Japan	12/28/99	YES
2000-68364	Japan	03/13/00	YES
<u>2000-68366</u>	<u>Japan</u>	<u>03/13/00</u>	<u>YES</u>
2000-121629	Japan	04/21/00	YES
2000-147591	Japan	05/19/00	YES
11-375753	Japan	12/28/99	YES

ASSIGNMENT INFORMATION

Assignee Name:: TDK Corporation

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